# BZX84WCx Zener Voltage Regulator Diode in SC-70

## 1 Features

- Total power dissipation: 360mW (max)
- Tolerance: ±5%
- Temperature range: -55°C to +150°C
- Leaded package used for automatic optical inspection (AOI)

## 2 Applications

- Voltage regulation
- Over-voltage protection

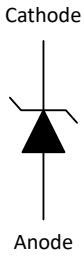
## 3 Description

The BZX84WCx is a family of voltage regulating diodes in a SC-70 package. The diodes are available in Zener voltages ranging from 5.6V to 39V.

**Package Information**

| PART NUMBER | PACKAGE (1) | PACKAGE SIZE (2) |
|---|---|---|
| BZX84WCx | DCK (SC-70, 3) | 2.00mm × 2.10mm |

(1) For more information, see Section 9.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.




**Functional Block Diagram**

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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# 4 Related Products

| ZENER FAMILY | POWER DISSIPATION | PACKAGE |
|---|---|---|
| BZX84Cx / BZX84Cx-Q1 | 430mW | SOT-23 |
| BZX84WCx / BZX84WCx-Q1 | 360mW | SC-70 |
| BZX884Cx / BZX884Cx-Q1 | 250mW | DFN1006 |
| SZMM3Zx (1) / SZMM3Zx-Q1 (1) | 300mW | SOD323 |
| SZMM5Zx (1) / SZMM5Zx-Q1 (1) | 290mW | SOD523 |

(1) Preview Information (not Production Data)

# 5 Pin Configuration and Functions

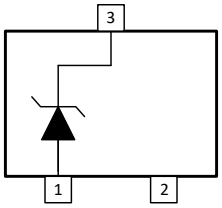


**Figure 5-1. DCK Package, 3-Pin SC-70 (Top View)**

**Table 5-1. Pin Functions**

| PIN | | DESCRIPTION |
|---|---|---|
| NO. | NAME | |
| 1 | A | Anode |
| 2 | NC | No Connect |
| 3 | K | Cathode |

# 6 Specifications

## 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

| | | MIN | MAX | UNIT |
|---|---|---|---|---|
| $P_D$ (2) (3) | Total Power Dissipation | | 360 | mW |
| $T_A$ | Ambient Operating Temperature | -55 | 150 | °C |
| $T_{stg}$ | Storage Temperature | -65 | 155 | °C |

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If briefly operating outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) FR-4 printed circuit board, single sided copper, standard footprint
(3) Measured at 25℃

## 6.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | NOM | MAX | UNIT |
|---|---|---|---|---|---|---|
| $V_F$ | Forward Voltage | $I_F$ = 10 mA | | | 0.9 | V |
| $T_A$ | Operating free-air temperature | | -55 | | 150 | °C |

## 6.3 Thermal Information

| THERMAL METRIC (1) | | BZX84WCx DCK (SC-70) 3 PINS | UNIT |
|---|---|---|---|
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 345.0 | °C/W |
| $R_{\theta JC(top)}$ | Junction-to-case (top) thermal resistance | 223.0 | °C/W |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 159.0 | °C/W |
| $\Psi_{JT}$ | Junction-to-top characterization parameter | 113.6 | °C/W |
| $\Psi_{JB}$ | Junction-to-board characterization parameter | 157.9 | °C/W |
| $R_{\theta JC(bot)}$ | Junction-to-case (bottom) thermal resistance | N/A | °C/W |

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application note.

## 6.4 Electrical Characteristics

At $T_A$ = 25°C (unless otherwise noted)

| Part Number | Zener Voltage $V_Z$ (V) at $I_Z$ | | | | Zener Impedance $Z_{ZT}$ (Ω) at $I_Z$ | | Reverse Leakage Current $I_R$ (µA) | | Temperature Coefficient $S_Z$ (mV/C) at $I_Z$ | | Capacitance $C_D$ (pF) (1) |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | MIN | TYP | MAX | $I_Z$ (mA) | MAX | $I_Z$ (mA) | MAX | $V_R$ (V) | MAX | $I_Z$ (mA) | MAX |
| BZX84WC5V6 | 5.2 | 5.6 | 6 | 5 | 40 | 5 | 0.75 | 2 | 2.5 | 5 | 200 |
| BZX84WC6V8 | 6.4 | 6.8 | 7.2 | 5 | 15 | 5 | 0.1 | 4 | 4.5 | 5 | 120 |
| BZX84WC8V2 | 7.79 | 8.2 | 8.61 | 5 | 15 | 5 | 0.6 | 5.75 | 6.2 | 5 | 80 |
| BZX84WC9V1 | 8.5 | 9.1 | 9.6 | 5 | 15 | 5 | 0.2 | 6 | 8 | 5 | 90 |
| BZX84WC15V | 14.25 | 15 | 15.75 | 5 | 30 | 5 | 0.03 | 10.5 | 13 | 5 | 50 |
| BZX84WC16V | 15.3 | 16 | 17.1 | 5 | 40 | 5 | 0.03 | 11.2 | 15.5 | 5 | 50 |
| BZX84WC18V | 16.8 | 18 | 19.1 | 5 | 45 | 5 | 0.03 | 12.6 | 19 | 5 | 45 |
| BZX84WC27V | 25.65 | 27 | 28.35 | 2 | 80 | 2 | 0.03 | 18.9 | 25.3 | 2 | 35 |
| BZX84WC33V | 31 | 33 | 35 | 2 | 90 | 2 | 0.03 | 23.1 | 37.5 | 2 | 30 |
| BZX84WC39V | 37.05 | 39 | 40.95 | 2 | 130 | 2 | 0.03 | 27.3 | 41.2 | 2 | 25 |

(1) f = 1MHz, $V_R$ = 0


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## 6.5 Typical Characteristics

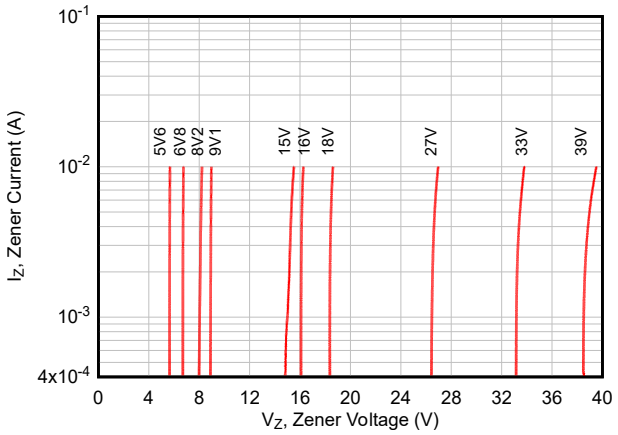


**Figure 6-1. Zener Current vs Zener Voltage**

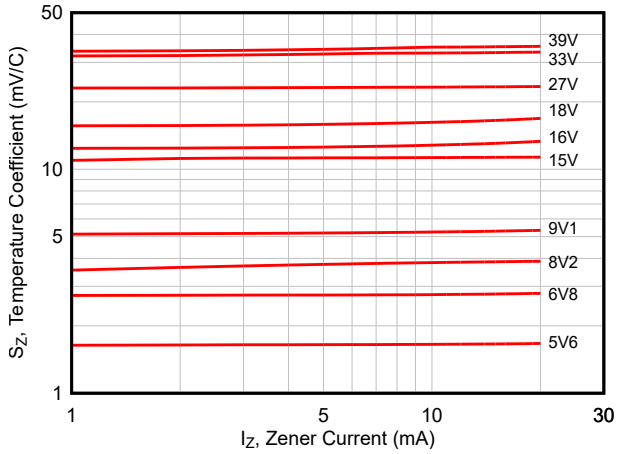


**Figure 6-2. Temperature Coefficient**

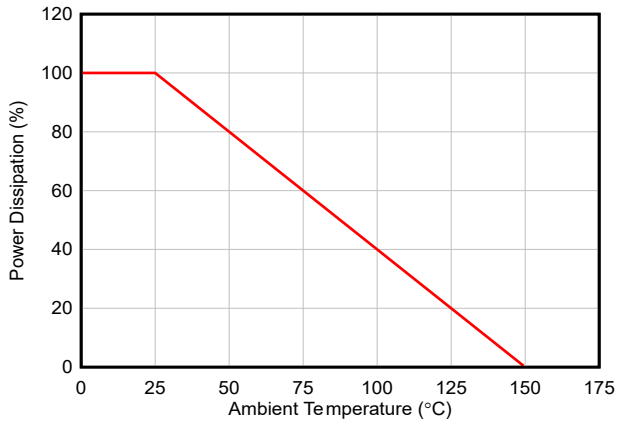


**Figure 6-3. Power Derating Curve**

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# 7 Device and Documentation Support

## 7.1 Documentation Support

### *7.1.1 Related Documentation*

For related documentation, see the following:

- Texas Instruments, *Diodes Packaging and Layout Guide*
- Texas Instruments, *Diodes Layout Guide user's guide*
- Texas Instruments, *Generic Evaluation Module user's guide*

## 7.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

## 7.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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## 7.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 7.6 Glossary

| | |
|---|---|
| TI Glossary | This glossary lists and explains terms, acronyms, and definitions. |


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## 8 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision B (November 2025) to Revision C (March 2026) | Page |
|---|---|
| • Added BZX84WC33V to the datasheet | 1 |

| Changes from Revision A (April 2025) to Revision B (November 2025) | Page |
|---|---|
| • Added BZX84WC5V6, BZX84WC6V8, BZX84WC9V1, BZX84WC16V, BZX84WC18V devices | 1 |

| Changes from Revision * (February 2025) to Revision A (April 2025) | Page |
|---|---|
| • Added BZX84WC39V device | 1 |

| DATE | REVISION | NOTES |
|---|---|---|
| February 2025 | * | Initial Release |

## 9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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## PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type (2) | Package \| Pins | Package qty \| Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|---|---|---|---|---|---|---|---|---|---|
| BZX84WC15VDCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 1UM |
| BZX84WC16VDCKR | Active | Production | null (null) \| | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | - | 1ZN |
| BZX84WC18VDCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | - | 1ZO |
| BZX84WC27VDCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 1UN |
| BZX84WC27VDCKR.B | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 1UN |
| BZX84WC33VDCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 24B |
| BZX84WC39VDCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 1T3 |
| BZX84WC39VDCKR.B | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 1T3 |
| BZX84WC5V6DCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | - | 1ZP |
| BZX84WC6V8DCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | - | 1ZR |
| BZX84WC8V2DCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 1T1 |
| BZX84WC8V2DCKR.B | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -55 to 150 | 1T1 |
| BZX84WC9V1DCKR | Active | Production | SC70 (DCK) \| 3 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | - | 1ZQ |

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**OTHER QUALIFIED VERSIONS OF BZX84WC15V, BZX84WC16V, BZX84WC18V, BZX84WC27V, BZX84WC33V, BZX84WC39V, BZX84WC5V6, BZX84WC6V8, BZX84WC8V2, BZX84WC9V1 :**

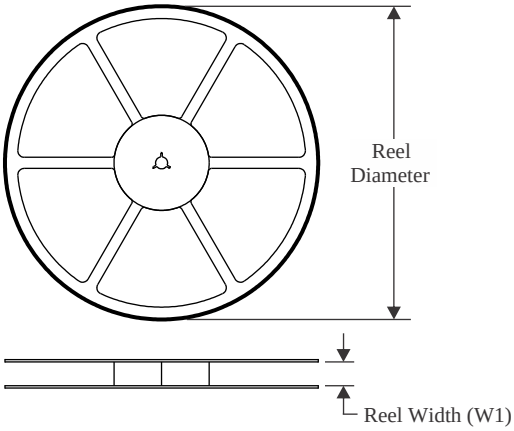
- Automotive : BZX84WC15V-Q1, BZX84WC16V-Q1, BZX84WC18V-Q1, BZX84WC27V-Q1, BZX84WC33V-Q1, BZX84WC39V-Q1, BZX84WC5V6-Q1, BZX84WC6V8-Q1, BZX84WC8V2-Q1, BZX84WC9V1-Q1

NOTE: Qualified Version Definitions:

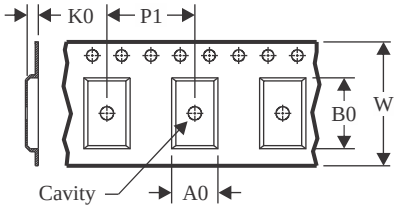
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

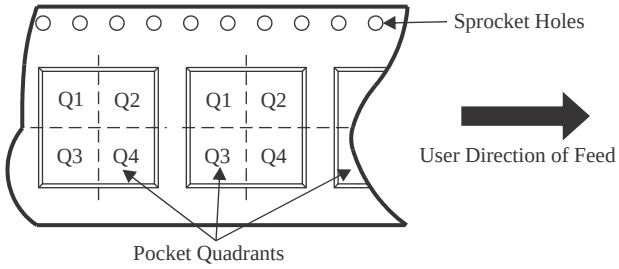



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

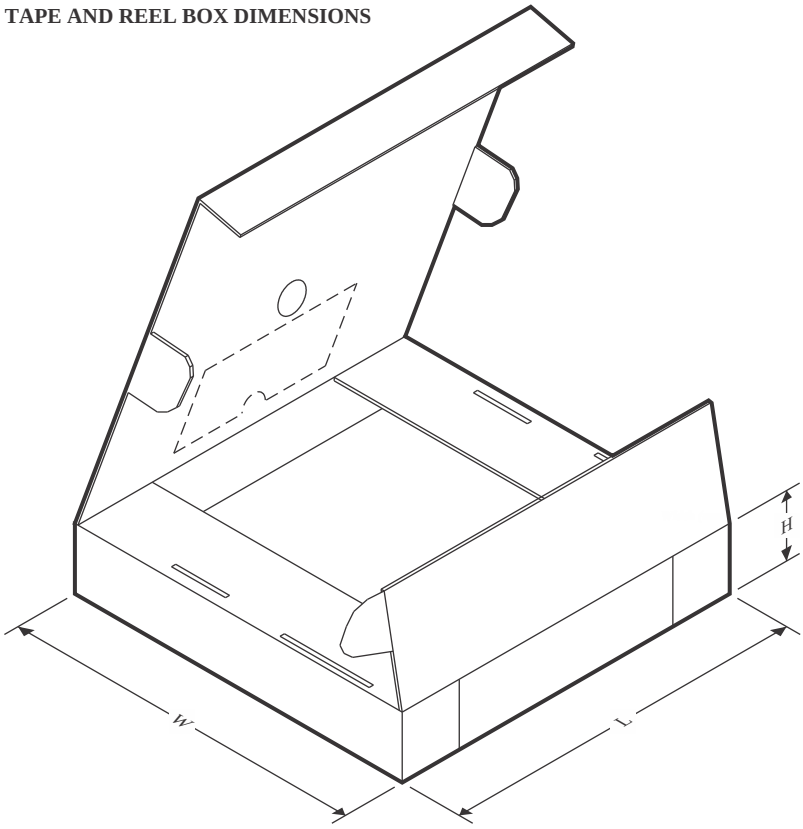
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| BZX84WC15VDCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC18VDCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC27VDCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC33VDCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC39VDCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC5V6DCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC6V8DCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC8V2DCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |
| BZX84WC9V1DCKR | SC70 | DCK | 3 | 3000 | 180.0 | 8.4 | 2.3 | 2.75 | 1.2 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

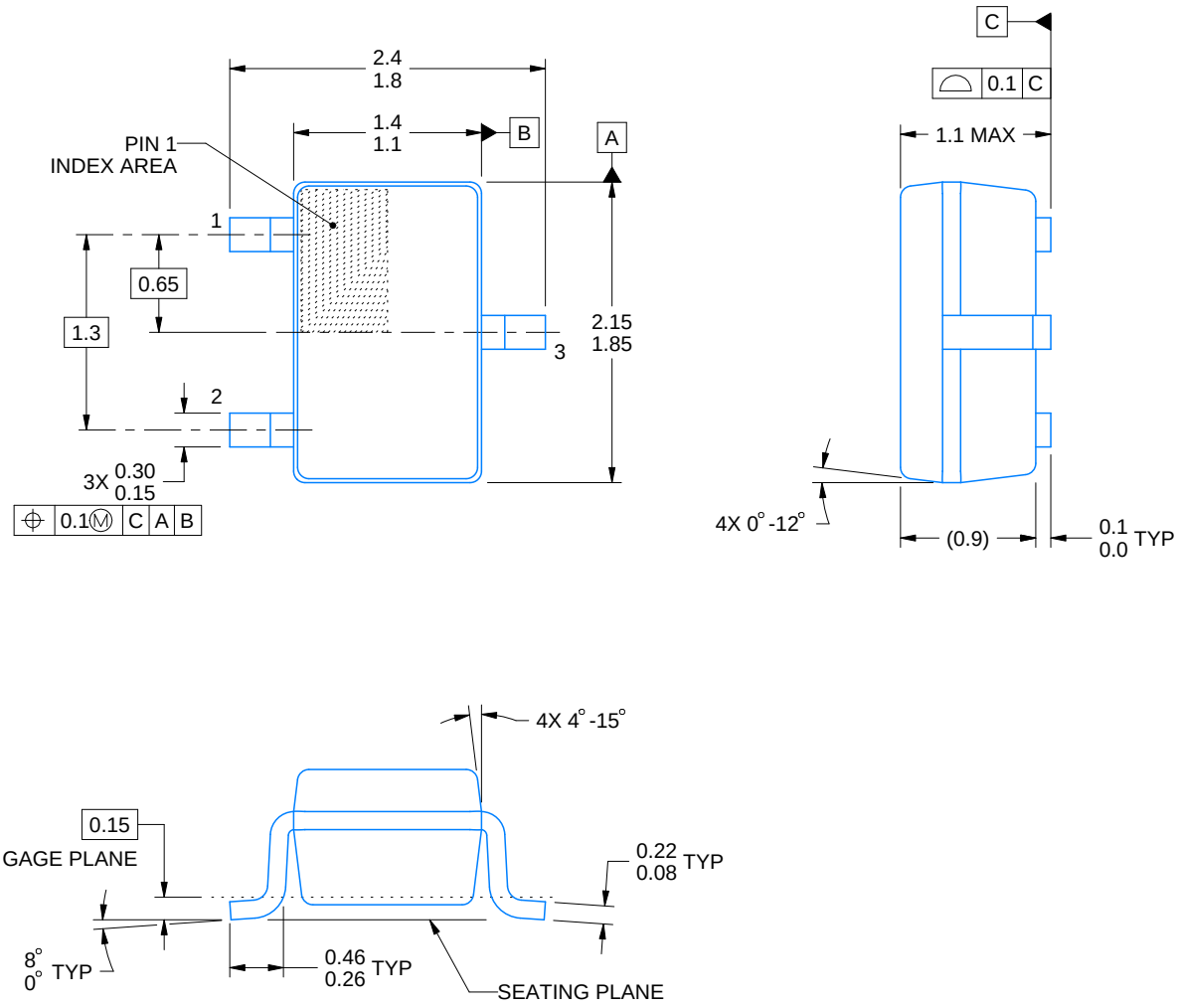
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| BZX84WC15VDCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC18VDCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC27VDCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC33VDCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC39VDCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC5V6DCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC6V8DCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC8V2DCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |
| BZX84WC9V1DCKR | SC70 | DCK | 3 | 3000 | 210.0 | 185.0 | 35.0 |

# PACKAGE OUTLINE

## DCK0003A

## SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70

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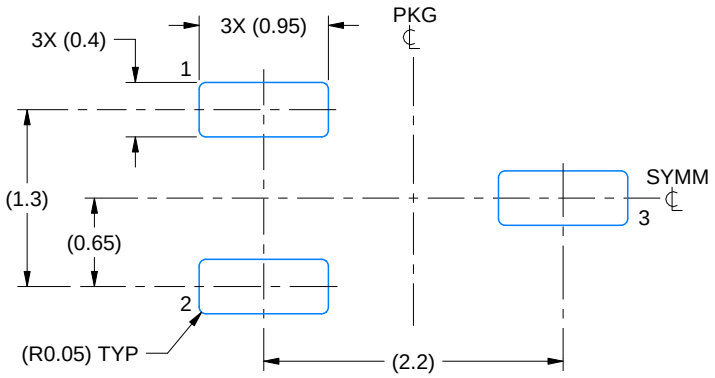
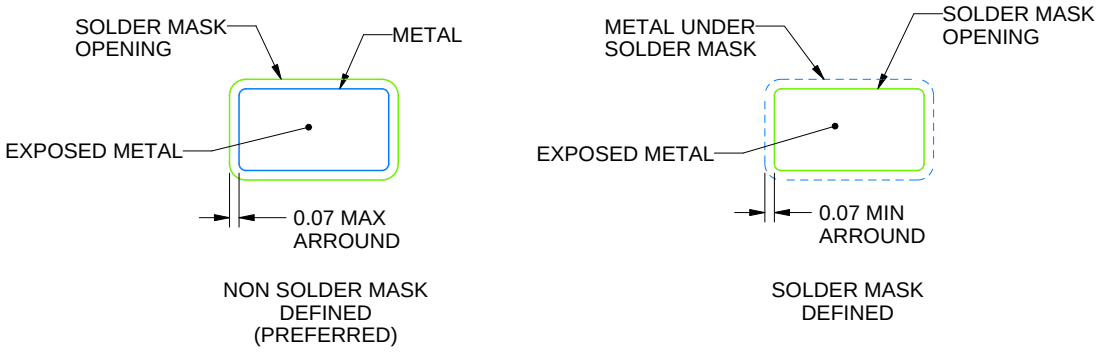
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X




SOLDER MASK DETAILS

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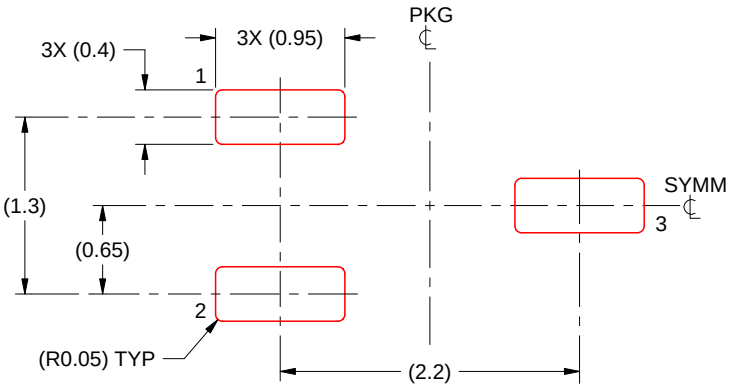
NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.




SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4220745/F 11/2024

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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